MOS FET

FC8J33040L

Panasonic

FC8J33040L

Dual N-channel MOSFET

For switching For DC-DC Converter

■ Features

- Low drain-source On-state Resistance : RDS(on) typ = 48 m Ω (VGS = 4.5 V)
- High-speed switching : Qg = 2.8 nC
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 7A
- Basic Part Number: Dual Nch MOS 33V (Individual)

■ Packaging

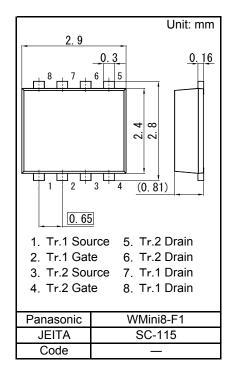
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

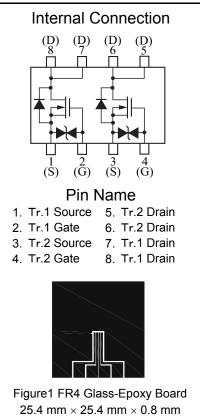
Absolute Maximum Ratings Ta = 25 °C Tr.1, Tr.2

Parameter	Symbol	Rating	Unit			
Drain-source Voltage	VDS	33	V			
Gate-source Voltage	VGS	±20	V			
Drain Current (Steady State) *1	ID	5				
Drain Current (t = 10 s) *1	טו	5.5				
Drain Current (Pulsed) *1,*2	IDp	20	Α			
Source Current (Pulsed)	ISp	5				
(Body Diode) *1,*2	(BD)	5	<u> </u>			
Total Power Dissipation (Steady State) *1	PD	1	W			
Total Power Dissipation (t = 10 s) *1	וו	1.3	VV			
Channel Temperature	Tch	150	°C			
Operating Ambient Temperature	Topr	-40 to + 85	°C			
Storage Temperature Range	Tstg	-55 to +150	°C			
11 (1) 11 11 11 11 11 11 11 11						

Note) *1 Device mounted on a glass-epoxy board (See Figure 1)

*2 Pulse test: Ensure that the channel temperature does not exceed 150°C.





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Revision. 2

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■ Electrical Characteristics Ta = 25° C $\pm 3^{\circ}$ C Tr.1, Tr.2

Static Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source Breakdown Voltage	VDSS	ID = 1 mA, VGS = 0 V	33			V
Zero Gate Voltage Drain Current	IDSS	VDS = 33 V, VGS = 0 V			1	μΑ
Gate-source Leakage Current	IGSS	VGS = ±16 V, VDS = 0 V			±10	μΑ
Gate-source Threshold Voltage	Vth	ID = 0.26 mA, VDS = 10 V	1		2.5	V
		ID = 2.5 A, VGS = 10 V		32	38	mΩ
	RDS(on)2	ID = 2.5 A, VGS = 4.5 V		48	68	

Dynamic Characteristics
Input Capacitance

Coss	VDS - 10 V, VGS - 0 V	4.0	
	VDS = 10 V, VGS = 0 V f = 1 MHz	40	pF
Crss	1 - 1 1011 12	35	
td(on)	VDD = 15 V, VGS = 0 to 10 V	7	
tr	ID = 2.5 A	3	ns
td(off)	VDD = 15 V, VGS = 10 to 0 V	15	113
tf	ID = 2.5 A	9	
Qg	VDD = 15 V VGS = 0 to 4.5 V	2.8	
Qgs	-	1.1	nC
Qgd	10-37	1.2	
	td(on) tr td(off) tf Qg Qgs	td(on) VDD = 15 V, VGS = 0 to 10 V tr ID = 2.5 A td(off) VDD = 15 V, VGS = 10 to 0 V tf ID = 2.5 A Qg VDD = 15 V, VGS = 0 to 4.5 V, ID = 5 A	td(on) VDD = 15 V, VGS = 0 to 10 V 7 tr ID = 2.5 A 3 td(off) VDD = 15 V, VGS = 10 to 0 V 15 tf ID = 2.5 A 9 Qg VDD = 15 V, VGS = 0 to 4.5 V, 1.1

Body Diode Characteristic

Diode Forward Voltage *1	VSD	IS = 2.5 A, VGS = 0 V	8.0	1.2	V

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

Established: 2011-01-13 Revised: 2013-07-31

^{2. *1} Pulse test: Ensure that the channel temperature does not exceed 150°C.

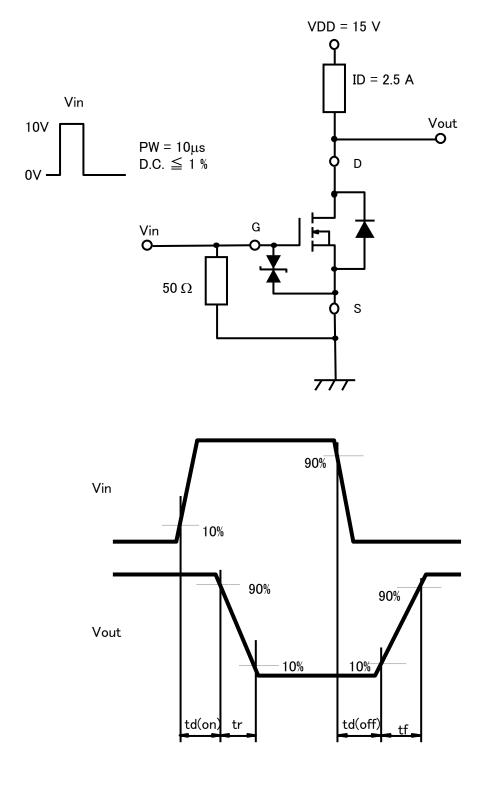
^{*2} Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time

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*2 Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time

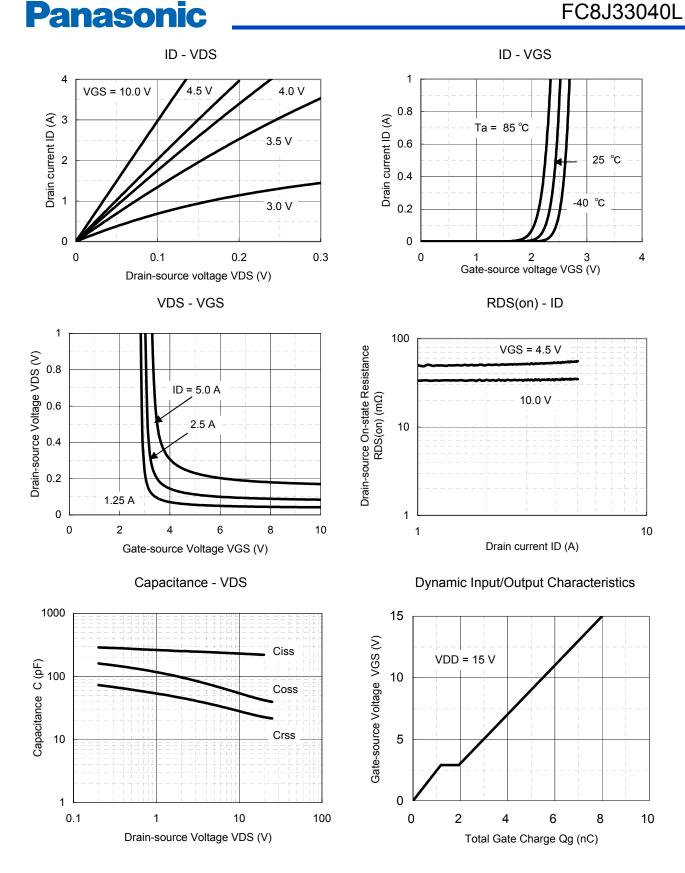


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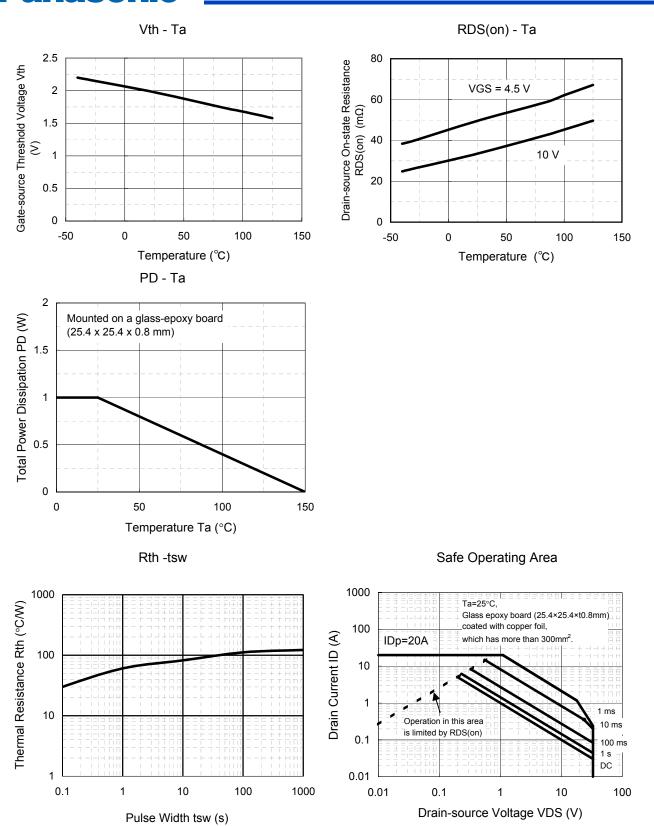
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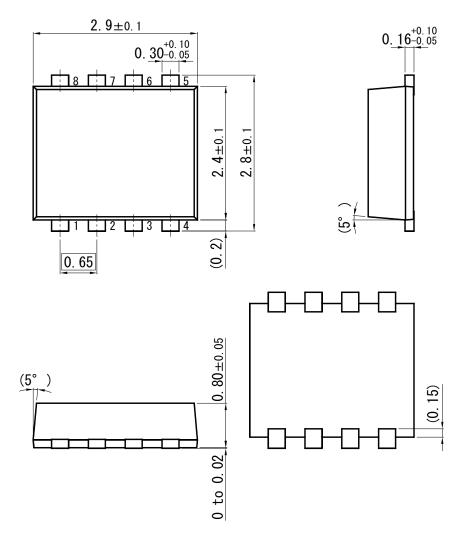
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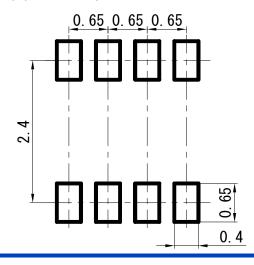
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WMini8-F1

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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